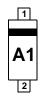


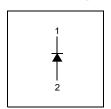
March 2010

BAS16HT1G Small Signal Diode





Connection Diagram



Absolute Maximum Ratings * T_A = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V _{RRM}	Maximum Repetitive Reverse Voltage	85	V
I _{F(AV)}	Average Rectified Forward Current	200	mA
I _{FSM}	Non-repetitive Peak Forward Surge Current Pulse Width = 1.0 second	600	mA
T _{STG}	Storage Temperature Range	-65 to +150	°C
TJ	Operating Junction Temperature	-55 to +150	°C

^{*} These ratings are limiting values above which the serviceability of the diode may be impaired.

NOTES:

- 1) These ratings are based on a maximum junction temperature of 150 degrees C.
- 2) These are steady limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Thermal Characteristics

Symbol	Parameter	Value	Units
P _D	Power Dissipation	200	mW
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	600	°C/W

Electrical Characteristics $T_A = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V _R	Breakdown Voltage	I _R = 5.0μA	85		V
V _F	Forward Voltage	$I_F = 0.1 \text{mA}$ $I_F = 10 \text{mA}$ $I_F = 50 \text{mA}$ $I_F = 150 \text{mA}$		715 855 1.0 1.25	mV mV V
I _R	Reverse Leakage	V _R = 75V V _R = 25V, T _A = 150°C V _R = 75V, T _A = 150°C		1.0 30 50	μΑ μΑ μΑ
C _T	Total Capacitance	V _R = 0, f = 1.0MHz		2.0	pF
t _{rr}	Reverse Recovery Time	$I_F = I_R = 10 \text{mA}, I_{RR} = 1.0 \text{mA},$ $R_L = 100 \Omega$		6.0	ns

1

Typical Performance Characteristics

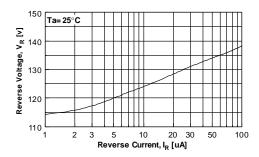


Figure 1. Reverse Voltage vs Reverse Current BV - 1.0 to $100\mu A$

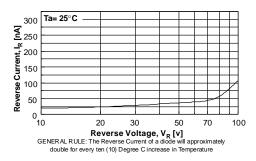


Figure 2. Reverse Current vs Reverse Voltage IR - 10 to 100V

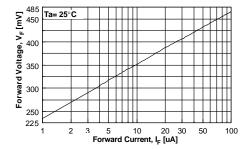


Figure 3. Forward Voltage vs Forward Current VF - 1.0 to $100\mu A$

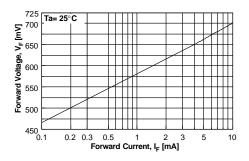


Figure 4. Forward Voltage vs Forward Current VF - 0.1 to 10mA

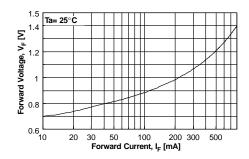


Figure 5. Forward Voltage vs Forward Current VF - 10 - 800mA

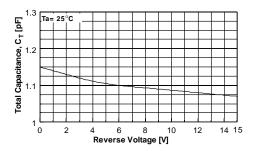
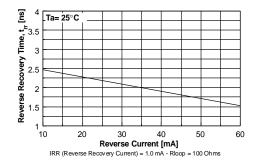


Figure 6. Total Capacitance

Typical Performance Characteristics (Continued)



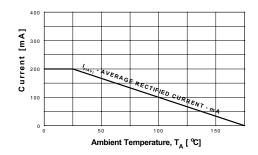


Figure 1. Reverse Recovery Time vs Reverse Current TRR - IR 10mA vs 60mA

Figure 2. Average Rectified Current $(I_{F(AV)})$ vs Ambient Temperature (T_A)

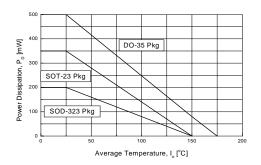
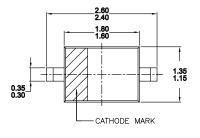
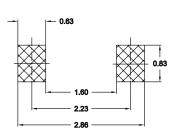


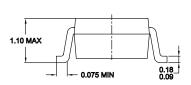
Figure 3. Power Derating Curve

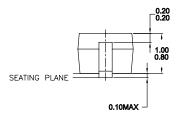
Physical Dimension

SOD-323









NOTES: UNLESS OTHERWISE SPECIFIED
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Dimensions in Millimeters





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Definition of Terms				
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